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***Embedded thermoelectric cooler technology firm adds thermal expert...***

## **NEXTREME THERMAL SOLUTIONS NAMES NEW CHIEF TECHNOLOGY OFFICER**

Research Triangle Park, N.C. (February 7, 2007) – Nextreme Thermal Solutions, a manufacturer of advanced thin film thermoelectric components designed and produced to address the thermal management needs of the electronics, photonics, bio-tech and defense/aerospace industries, has recently appointed Dr. Seri Lee as Chief Technology Officer. Prior to joining Nextreme, Dr. Lee served as Senior Thermal Scientist for the Silicon and Platform Solutions Group at Intel Corporation, where he was responsible for executing corporate thermal directions for consumer products and technology development requirements. As an active member of the ASME Heat Transfer Division K-16 Committee on Heat Transfer in Electronic Equipment and the IEEE/SemiTherm Executive Committee, Dr. Lee brings a wide range of thermal management experience to Nextreme.

“I am excited to welcome Dr. Lee to Nextreme, as his experience is a part of our plan to build a world-class technology team focusing on electronic and opto-electronic packaging and thermal management,” said Jesko von Windheim, CEO at Nextreme. “I believe that Dr. Lee’s addition positions the company to address many of the most demanding issues in thermal management for advanced technology products; in addition, Dr. Lee will bring a new focus to the company’s efforts in the area of thermoelectric power generation.”

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Dr. Lee has also previously held positions at Amkor Technology as Manager of Thermal Characterization, Aavid Thermal Technologies as Director of Advanced Thermal Engineering and at the University of Waterloo in Ontario as Assistant Professor of Mechanical Engineering.

“Throughout my career, I have enjoyed the challenge of directing thermal technology advancement projects,” said Dr. Lee. “I look forward to continuing that role and increasing our knowledge of our customers’ needs in order to offer them industry-leading solutions that will help them in all aspects of their business.”

In addition, Dr. Lee has organized numerous technical programs and sessions, published more than 60 technical papers and holds 16 patents covering a wide range of thermal issues in electronics. Dr. Lee served as the General Chair for the 1998 IEEE SemiTherm International Symposium, and in 2004 he received the best paper award from the ASME Journal of Heat Transfer Division.

“Dr. Lee is a great asset to Nextreme,” said Richard Harris, Chairman of the Board at Nextreme. “We look forward to his contributions as a member of Nextreme’s technology team to position the company for continued growth and success.”

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### **About Nextreme Thermal Solutions**

Nextreme Thermal Solutions manufactures advanced thin film thermoelectric components to address the thermal management needs of the semiconductor, photonics, test-and-measurement and defense/aerospace industries. These high-performance solid-state components operate as miniature heat pumps for cooling semiconductors and other electronics, and for thermal management of fiber-optic laser controls and integrated optoelectronics. Nextreme's unique thin-film technology provides an industry first - the embedding of an active cooling device in close proximity to the die of an integrated circuit. Other applications include converting heat into electricity for advanced power generation applications, thermal batteries and automotive energy management.

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